



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





P/N 1110748 Surface Mount-to-DIP JEDEC SOT-25, SOT-23A-6 Adapter

FEATURES

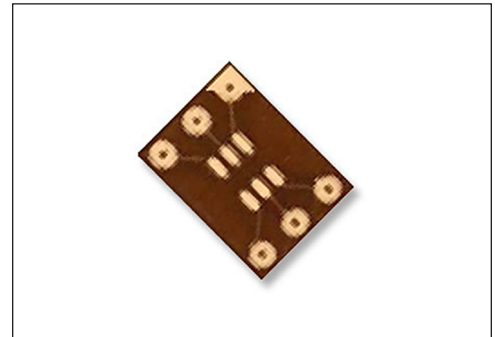
- Allows for breadboarding or substitution of Microgate SOT-23A-6 and SOT-25 IC and transistor packages into 0.100 [2.54] pitch proto boards or PC boards.
- Solder masked top-side pads allow user to hand solder devices directly to topside of adapter with fewer problems of solder bridging.
- Longer male bottom Pins available at special request for easy use of probe clips.
- Large topside pads allow for soldering test pins, jumpers, etc. to top of adapter.

GENERAL SPECIFICATIONS

- BOARD MATERIAL: 0.062 [1.58] thick FR-4 manufactured to IPC-600E, Class 2 standards, with 1-oz. Cu traces, both sides
- PADS: HASL
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 200 μ [5.08 μ] Sn/Pb 93/7 ASTM B579-73 over 100 μ [2.54 μ] Ni per SAE-AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 \pm 0.003 [0.71 \pm 0.08] dia.



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

P/N 1110748

P/N 1110748-P for Panelized Version

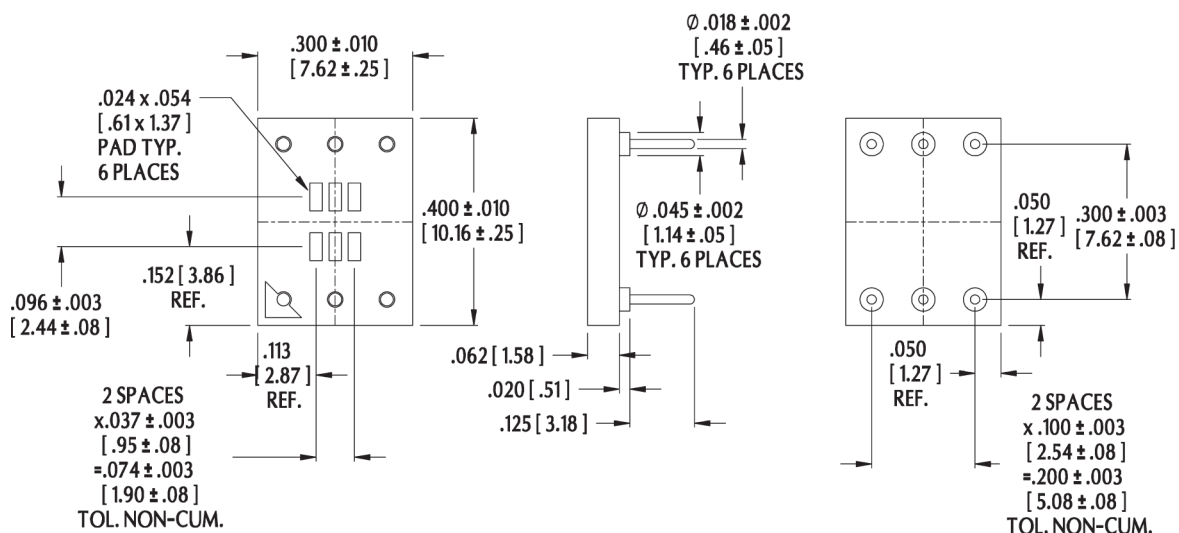
ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: \pm 0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ALL CAC's ARE MANUFACTURED ND INSPECTED USING IPC -610B CLASS 2 GUIDELINES

CONSULT FACTORY FOR MOUNTING CONSIDERATIONS OF CONSIGNED CHIPS.

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



ARIES
ELECTRONICS, INC.

Bristol, PA 19007-6810 USA
TEL (215) 781-9956 • FAX (215) 781-9845
WWW.ARIESELEC.COM • INFO@ARIESELEC.COM

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